Product Preview

50A, Ultra Low Capacitance TSPD

The NP-SAMC series of Low Capacitance Thyristor Surge Protection Devices (TSPD) protect sensitive electronic equipment from transient overvoltage conditions. Due to their ultra low off-state capacitance (C₀), they offer minimal signal distortion for high speed equipment such as DSL and T1/E1 circuits. The low nominal offstate capacitance translates into the extremely low differential capacitance offering superb linearity with applied voltage or frequency.

The NP-SAMC Series helps designers to comply with the various regulatory standards and recommendations including: GR-1089-CORE, IEC 61000-4-5, ITU K.20/K.21/K.45, IEC 60950, TIA-968-A, FCC Part 68, EN 60950, UL 1950.

Features

- Ultra Low Micro Capacitance
- Low Leakage (Transparent)
- High Surge Current Capabilities
- Precise Turn on Voltages
- Low Voltage Overshoot
- These are Pb-Free Devices

Typical Applications

- xDSL Central Office and Customer Premise
- T1/E1
- Other Broadband High Speed Data Transmission Equipment

ELECTRICAL CHARACTERISTICS

	V _{DRM}	V _(BO)	C _O , 2 V, 1 MHz	C _O , 50 V, 1 MHz
Device	V	V	pF (Max)	pF (Max)
NP0640SAMCT3G	± 58	± 77	18	8
NP0720SAMCT3G	±65	±88	18	8
NP0900SAMCT3G	± 75	±98	18	8
NP1100SAMCT3G	±90	±130	18	8
NP1300SAMCT3G	±120	±160	18	8
NP1500SAMCT3G	± 140	± 180	18	8
NP1800SAMCT3G	± 170	±220	18	8
NP2100SAMCT3G	± 180	± 240	18	8
NP2300SAMCT3G	± 190	±260	18	8
NP2600SAMCT3G	± 220	±300	18	8
NP3100SAMCT3G	± 275	±350	18	8
NP3500SAMCT3G	±320	±400	18	8

G in part number indicates RoHS compliance

Other protection voltages are available upon request

Symmetrical Protection - Values the same in both negative and positive excursions

(See V-I Curve on page 3)

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.



ON Semiconductor®

http://onsemi.com

ULTRA LOW CAPACITANCE BIDIRECTIONAL SURFACE MOUNT THYRISTOR 50A, 10x1000μs SURGE





SMB JEDEC DO-214AA CASE 403C

MARKING DIAGRAM



= Assembly Location

= Year ww = Work Week

= Specific Device Code (NPxxx0SAMC)

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]		
NPxxx0SAMCT3G	SMB (Pb-Free)	2500 Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SURGE RATINGS

	I _{PPS} A				I _{TSM} A	di/dt			
Waveform (μs)	2x10	8x20	10x160	10x560	10x360	10x1000	5x310	0.1 s 60 Hz	A/μs
Value	150	150	90	50	75	50	75	20	500

MAXIMUM RATINGS ($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Rating		Value	Unit
V_{DRM}	Repetitive peak off-state voltage: Rated maximum	NP0640SAMCT3G	± 58	V
	(peak) continuous voltage that may be applied in the off-state conditions including all dc and repetitive	NP0720SAMCT3G	± 65	
	alternating voltage components.	NP0900SAMCT3G	± 75	
		NP1100SAMCT3G	±90	
		NP1300SAMCT3G	± 120	
		NP1500SAMCT3G	± 140	
		NP1800SAMCT3G	± 170	
		NP2100SAMCT3G	± 180	
		NP2300SAMCT3G	± 190	
		NP2600SAMCT3G	± 220	
		NP3100SAMCT3G	± 275	
		NP3500SAMCT3G	±320	
I _{PPS}	Nonrepetitive peak pulse current: Rated maximum	2x10 μs, GR-1089-CORE	150	Α
	value of peak impulse pulse current that may be applied.	8x20 μs, IEC-61000-4-5	150	
		10x160 μs, TIA-968-A	90	
		10x560 μs, TIA-968-A	50	
		10x360 μs, GR-1089-CORE	75	
		10x1000 μs, GR-1089-CORE	50	
		5x310 μs, ITU-K.20/K.21/K.45	75	
I _{TSM}	Nonrepetitive peak on-state current: Rated maximum (peak) value of ac power frequency on-state surge current which may be applied for a specified time or number of ac cycles.	0.1s, 50/60 Hz, full sine wave	20	A

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

www.DataSheet4U.com

ELECTRICAL CHARACTERISTICS TABLE ($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Rating		Min	Тур	Max	Unit
V _(BO)	Breakover voltage: The maximum voltage across the device in or at the	NP0640SAMCT3G			± 77	V
	breakdown region. VDC = 1000 V, dv/dt = 100 V/μs	NP0720SAMCT3G			±88	
		NP0900SAMCT3G			±98	
		NP1100SAMCT3G			± 130	
		NP1300SAMCT3G			± 160	
		NP1500SAMCT3G			± 180	
		NP1800SAMCT3G			± 220	
		NP2100SAMCT3G			± 240	
		NP2300SAMCT3G			± 260	
		NP2600SAMCT3G			±300	
		NP3100SAMCT3G			±350	
		NP3500SAMCT3G			± 400	
I _(BO)	Breakover Current: The instantaneous current flowing at the breakover v	oltage.			800	mA
lΗ	Holding Current: The minimum current required to maintain the device in	the on-state.	150			mA
I _{DRM}	Off-state Current: The dc value of current that results from the applica-	V _D = 50 V			2	μΑ
	tion of the off-state voltage	$V_D = V_{DRM}$			5	
V _T	On–state Voltage: The voltage across the device in the on–state condition $I_T=2.2~A$ (pk), PW = 300 $\mu s,DC=2\%$	on.			4	V
dv/dt	Critical rate of rise of off-state voltage: The maximum rate of rise of voltage (below V_{DRM}) that will not cause switching from the off-state to the on-state. Linear Ramp between 0.1 V_{DRM} and 0.9 V_{DRM}		±5			kV/μs
di/dt	Critical rate of rise of on-state current: rated value of the rate of rise of con withstand without damage.	of the rate of rise of current which the device			±500	A/μs
Co	Off-state Capacitance	NP0640SAMCT3G			18	pF
	$f = 1.0 \text{ MHz}, V_d = 1.0 V_{RMS}, V_D = -2 \text{ Vdc}$	NP0720SAMCT3G			18	
		NP0900SAMCT3G			18	
		NP1100SAMCT3G			18	
		NP1300SAMCT3G			18	
		NP1500SAMCT3G			18	
		NP1800SAMCT3G			18	
		NP2100SAMCT3G			18	
		NP2300SAMCT3G			18	
		NP2600SAMCT3G			18	
		NP3100SAMCT3G			18	
		NP3500SAMCT3G			18	

THERMAL CHARACTERISTICS

	Symbol	Symbol Rating		Unit
D	ata J _{STG4U} Storage Temperature Range		-65 to +150	°C
	T_J	T _J Junction Temperature		°C
	R _{0JA} Thermal Resistance: Junction-to-Ambient Per EIA/JESD51-3, PCB = FR4 3"x4.5"x0.06" Fan out in a 3x3 inch pattern, 2 oz copper track.		90	°C/W

ELECTRICAL PARAMETER/RATINGS DEFINITIONS

Symbol	Parameter
V_{DRM}	Repetitive Peak Off-state Voltage
V _(BO)	Breakover Voltage
I _{DRM}	Off-state Current
I _(BO)	Breakover Current
I _H	Holding Current
V _T	On-state Voltage
I _T	On-state Current
I _{TSM}	Nonrepetitive Peak On-state Current
I _{PPS}	Nonrepetitive Peak Impulse Current
V _D	Off-state Voltage
I _D	Off-state Current

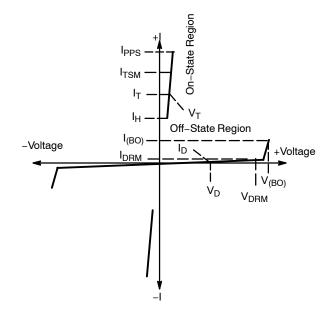


Figure 1. Voltage Current Characteristics of TSPD

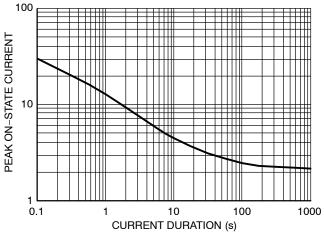


Figure 2. Nonrepetitive On-State Current vs. Time (I_{TSM})

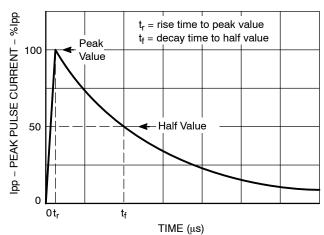


Figure 3. Nonrepetitive On-State Impulse vs. Waveform (I_{PPS})

Detailed Operating Description

The TSPD or <u>Thyristor Surge Protection Device</u> are specialized silicon based overvoltage protectors, used to protect sensitive electronic circuits from damaging overvoltage transient surges caused by induced lightning and powercross conditions.

The TSPD protects by switching to a low on state voltage when the specified protection voltage is exceeded. This is known as a "crowbar" effect. When an overvoltage occurs, the crowbar device changes from a high-impedance to a low-impedance state. This low-impedance state then offers

a path to ground, shunting unwanted surges away from the sensitive circuits.

This crowbar action defines the TSPD's two states of functionality: Open Circuit and Short Circuit.

<u>Open Circuit</u> – The TSPD must remain transparent during normal circuit operation. The device looks like an open across the two wire line.

<u>Short Circuit</u> – When a transient surge fault exceeds the TSPD protection voltage threshold, the devices switches on,

www.DataSheet4U.com

and shorts the transient to ground, safely protecting the circuit.

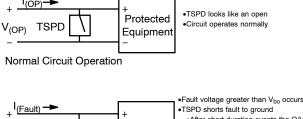




Figure 4. Normal and Fault Conditions

The electrical characteristics of the TSPD help the user to define the protection threshold for the circuit. During the open circuit condition the device must remain transparent; this is defined by the $I_{DRM}.$ The I_{DRM} should be as low as possible. The typical value is less than 5 $\mu A.$

The circuit operating voltage and protection voltage must be understood and considered during circuit design. The $V_{(BO)}$ is the guaranteed maximum voltage that the protected circuit will see, this is also known as the protection voltage. The V_{DRM} is the guaranteed maximum voltage that will keep the TSPD in its normal open circuit state. The TSPD $V_{(BO)}$ is typically a 20–30% higher than the V_{DRM} . Based on these characteristics it is critical to choose devices which have a V_{DRM} higher than the normal circuit operating voltage, and a $V_{(BO)}$ which is less than the failure threshold of the protected equipment circuit. A low on–state voltage V_t allows the TSPD to conduct large amounts of surge current (500 A) in a small package size.

Once a transient surge has passed and the operating voltage and currents have dropped to their normal level the TSPD changes back to its open circuit state.

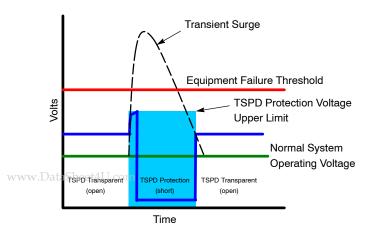


Figure 5. Protection During a Transient Surge

TSPD's are useful in helping designers meet safety and regulatory standards in Telecom equipment including GR-1089-CORE, ITU-K.20, ITU-K.21, ITU-K.45, FCC Part 68, UL1950, and EN 60950.

ON Semiconductor offers a full range of these products in the NP series product line.

DEVICE SELECTION

When selecting a TSPD use the following key selection parameters.

Off-State Voltage V_{DRM}

Choose a TSPD that has an Off-State Voltage greater than the normal system operating voltage. The protector should not operate under these conditions:

Example:

V_{DRM} should be greater than the peak value of these two components:

$$V_{DRM} > 212 + 48 = 260 V_{DRM}$$

Breakover Voltage V_(BO)

Verify that the TSPD Breakover Voltage is a value less than the peak voltage rating of the circuit it is protecting.

Example: Relay breakdown voltage, SLIC maximum voltage, or coupling capacitor maximum rated voltage.

Peak Pulse Current Ipps

Choose a Peak Pulse current value which will exceed the anticipated surge currents in testing. In some cases the 100 A "C" series device may be needed when little or no series resistance is used. When a series current limiter is used in the circuit a lower current level of "A" or "B" may be used. To determine the peak current divide the maximum surge current by the series resistance.

Hold Current (IH)

The Hold Current must be greater than the maximum system generated current. If it is not then the TSPD will remain in a shorted condition, even after a transient event has passed.

TYPICAL APPLICATIONS

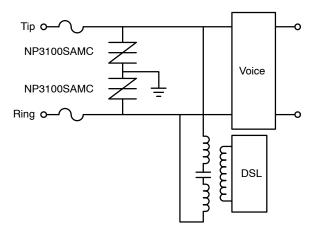


Figure 6. ADSL

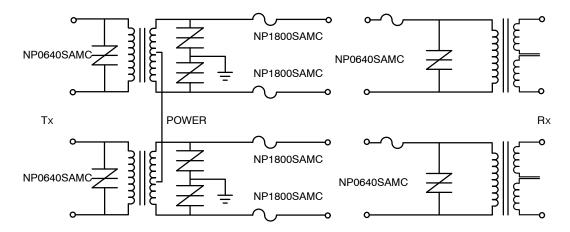
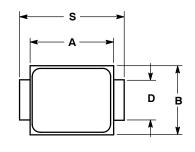


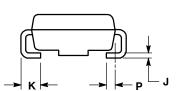
Figure 7. T1/E1

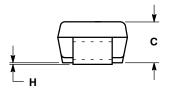
www.DataSheet4U.com

PACKAGE DIMENSIONS

SMB CASE 403C-01 ISSUE A





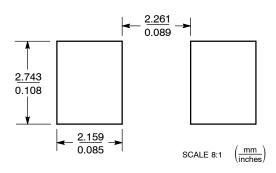


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.130	0.150	3.30	3.81	
C	0.075	0.095	1.90	2.41	
D	0.077	0.083	1.96	2.11	
Н	0.0020	0.0060	0.051	0.152	
7	0.006	0.012	0.15	0.30	
K	(0.030 0.050		0.76	1.27	
P	0.020 REF		0.51	REF	
S	0.205	0.220	5.21	5.59	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email: orderlit@onsemi.com

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative